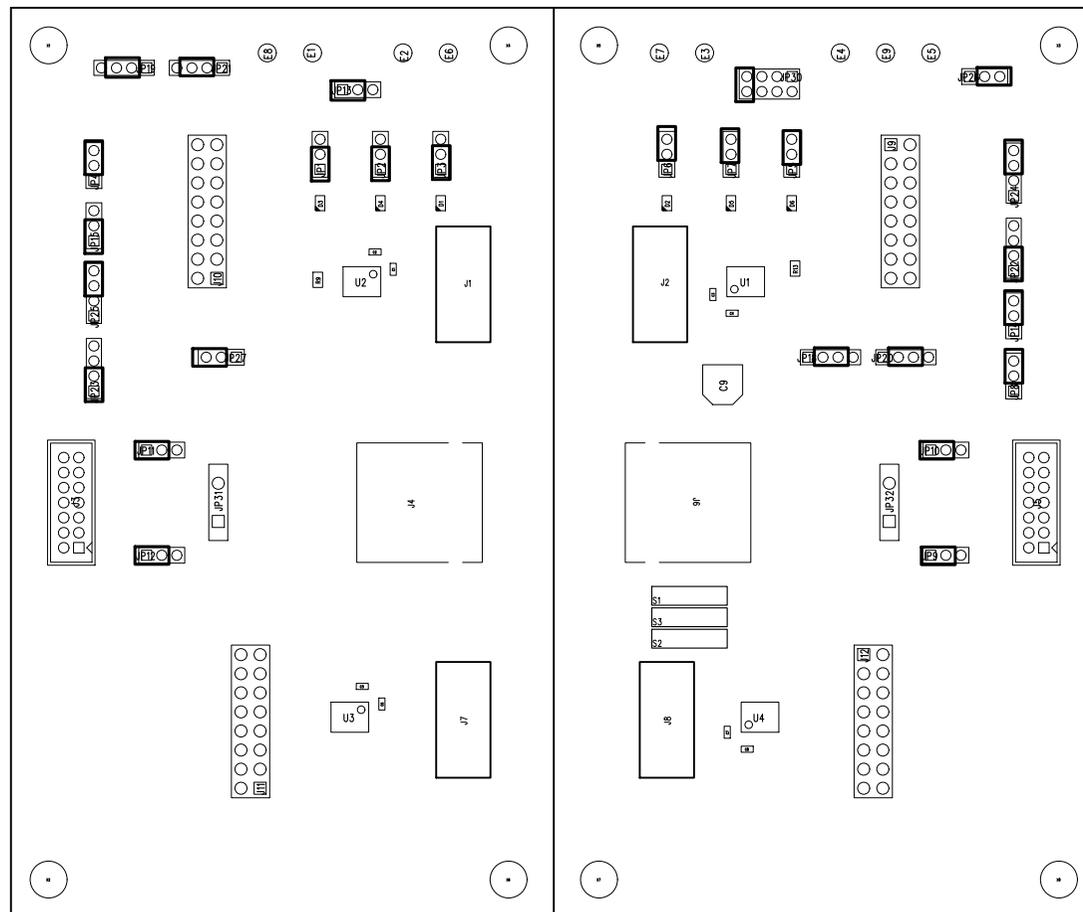


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
	3	Production	E Benedict	4 OCT 18



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. MAXIMUM SOLDER TEMPERATURE IS 250 DEG C.
3. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP AND BOTTOM SIDE SMD.
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
6. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
7. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
8. BREAK BOARDS AS A SET. DO NOT BREAK AT THIS LOCATION

APPROVALS

PCB DES. EB

APP ENG. EB



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TITLE: TOP ASSEMBLY DRAWING
DEMO CIRCUIT
RUGGED I2C SLAVE DEVICE EXTENDER

SIZE N/A	IC NO. LTC4331 DEMO CIRCUIT DC2754A	REV. 3
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SCALE = NONE

SHT 1 OF 2